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(54) Title: BONDED MICROFLUIDICS SYSTEM COMPRISING CMOS-CONTROLLABLE MICROFLUIDIC DEVICES

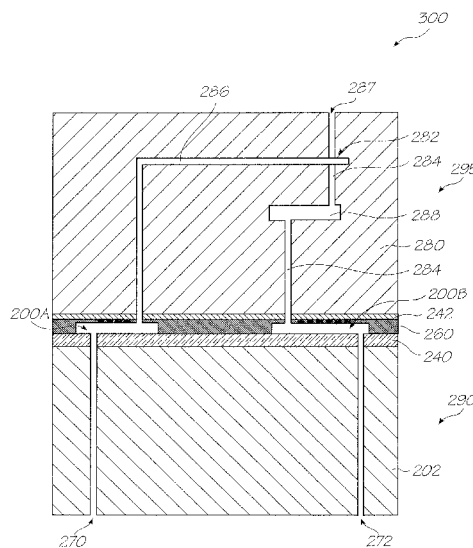


FIG. 8

(57) Abstract: A microfluidic system comprising an integrated circuit having a bonding surface bonded to a polymeric microfluidics platform. The microfluidic system comprises one or more microfluidics devices controlled by control circuitry in the integrated circuit. At least one of the microfluidic devices comprises a MEMS actuator positioned in a MEMS layer of the integrated circuit. The MEMS layer is covered with a polymeric layer which defines the bonding surface of the integrated circuit.